

 INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	ATTY DOCKET NO. RD27416-2	SERIAL NO. 10/638,099
	Gallucci et al.	
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PTO-1449			Attorney's Docket Number RD27416-2		Serial Number 10/638,099	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT LIST OF ITEMS (Use several sheets if necessary)			Name of Applicant Gallucci et al.			
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